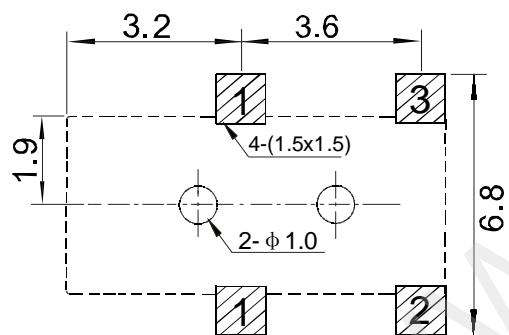
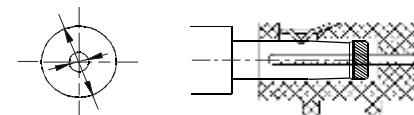
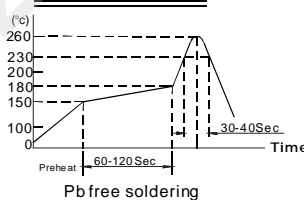


Circuit



Pad Layout

SOLDERING CONDITIONS



4	定位盖	1	PHOSPHOR BRONZE	鍍銀
3	接触片	1	PHOSPHOR BRONZE	鍍銀
2	接触针	1	PHOSPHOR BRONZE	鍍銀
1	基座	1	PPA	黑色
序號	名稱	數量	材料	電鍍



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: DC-096带柱 贴片	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC-DC096-750	MOLD NO.
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	DRAW NO: HYC-DC15111314	SHEET NO. 1 OF 1